





APPLICABLE STANDARD					
Rating	Operating Temperature Range	-55 °C to +85 °C ⁽¹⁾	Storage Temperature Range	-10 °C to +60 °C ⁽²⁾	
	Operating Humidity Range	Relative humidity 85 % max (Not dewed)	Storage Humidity Range	Relative humidity 85 % max (Not dewed)	
	Voltage	200 V AC	Applicable Cable	—	
	Current	1 A	Insulation	—	
SPECIFICATIONS					
ITEM	TEST METHOD	REQUIREMENTS	QT	AT	
CONSTRUCTION					
General Examination	Visually and by measuring instrument.	According to drawing.	x	x	
Marking	Confirmed visually.		x	x	
ELECTRIC CHARACTERISTICS					
Contact Resistance	100 mA (DC or 1000 Hz).	15 mΩ MAX .	x	—	
Insulation Resistance	500 V DC.	1000 MΩ MIN.	x	—	
Voltage Proof	650 V AC for 1 min.	No flashover or breakdown.	x	—	
MECHANICAL CHARACTERISTICS					
Mechanical Operation	100 times insertions and extractions.	1) Contact Resistance: 20 mΩ MAX. 2) No damage, crack and looseness of parts.	x	—	
Vibration	Frequency 10 to 55 Hz, single amplitude : 0.75 mm, 2 h in 3 directions.		1) No electrical discontinuity of 1 μs. 2) No damage, crack and looseness of parts.	x	—
Shock	490 m/s ² , duration of pulse 11 ms at 3 times for 3 both axial directions.			x	—
ENVIRONMENTAL CHARACTERISTICS					
Damp Heat (Steady state)	Exposed at 40 ± 2 °C, 90 to 95 %, 96 h.	1) Contact Resistance: 20 mΩ MAX. 2) Insulation Resistance: 1000 MΩ MIN. 3) No damage, crack and looseness of parts.	x	—	
Rapid Change of Temperature	Temperature -55 → +5 to +35 → +85 → +5 to +35 °C Time 30 → 10 to 15 → 30 → 10 to 15 min. Under 5 cycles.		x	—	
Corrosion Salt Mist	Exposed in 5 % salt water spray for 48 h.	1) Contact Resistance: 20 mΩ MAX. 2) No heavy corrosion.	x	—	
Sulphur Dioxide	Exposed in 10 PPM for 96 h. (Test standard: JEIDA 39)		x	—	
Resistance to Soldering Heat	Solder bath : solder temperature, 260 ± 5 °C for immersion,duration, 10 ± 1 s. (JISC5402-12-4, JISC60068-2-20)	No deformation of case of excessive looseness of the terminals.	x	—	
	Soldering irons : 360°C for 5 s MAX.		x	—	
Solderability	Soldered at solder temperature, 245 ± 3 °C, for immersion duration, 3 s.	A new uniform coating of solder shall cover a minimum of 95% of the surface being immersed.	x	—	
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	1	DIS-F-00004353	HR.NAGAYASU	HT.YAMAGUCHI	20190301
REMARK			APPROVED	NH.NAKATA	20170410
(1) Temperature rise included when energized. (2) This storage indicates A long-term storage state For the unused product before the board mounted. Unless otherwise specified, refer to IEC-60512. Clerical corrections. 			CHECKED	HT.YAMAGUCHI	20170410
			DESIGNED	HR.NAGAYASU	20170410
			DRAWN	HR.NAGAYASU	20170410
			Note	QT:Qualification Test AT:Assurance Test X:Applicable Test	DRAWING NO.
	SPECIFICATION SHEET		PART NO.	A3B- * PA-2DS(51)	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL621	 1/1